

PHOTOSENSITIVE RESIN, PHOTOSENSITIVE RESIN COMPOSITIONS CONTAINING THE SAME AND CURED ARTICLES OF THE COMPOSITIONS

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JP20010348344 20011114; JP20010355269 20011120

Cited documents:

-  JP7102037
-  JP2001100410
-  JP2001163948

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Abstract of WO02094904

A polyurethane compound (F) soluble in aqueous alkali, characterized by being prepared by reacting (A) an epoxy carboxylate compound obtained by reacting (a) an epoxy compound having two epoxy groups in the molecule with (b) a monocarboxylic acid compound having an ethylenically unsaturated double bond in the molecule with (B) a diisocyanate compound, (C) a carboxylic acid compound having two hydroxyl groups in the molecule, and, if necessary, (D) a diol compound other than the compounds (A) and (C) and/or (E) an epoxy compound having an ethylenically unsaturated group in the molecule. The photosensitive resin compositions of the invention are excellent in photosensitivity and can give cured articles excellent in flexibility, close adhesion, pencil hardness, solvent resistance, acid resistance, heat resistance, gold plating resistance, and so on.

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